Atty. Docket No. CPAC.1001-1 Appl. No. 09/802,443



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7-19.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE ?

Applicant: Rajendra D. PENDSE, et al.

Application No.: 09/802,443

Filed:

March 9, 2001

Title:

Flip chip-in-leadframe package and

process

Examiner: Deven M. Collins

Group Art Unit: 2823

Date: June 28, 2002

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Parents, Washington, D.C. 20231 on June 28, 2002.

Signed

COMMISSIONER OF PATENTS WASHINGTON, D.C. 20231

PRELIMINARY AMENDMENT
AND RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

# PRELIMINARY AMENDMENT

Preliminarily, kindly amend the application as follows:

# In the drawings:

Amend Fig. 4 as shown in red ink on the accompanying copy of drawings sheet numbered 2/2.

# RESPONSE TO RESTRICTION REQUIREMENT

Responsive to the Office Action mailed May 29, 2002 (Restriction Only), Applicants elect Group I, claims 1-14 for prosecution in this application.

### REMARKS

### Preliminary Amendment

Fig. 4 is amended to correct an obvious error made in preparation of formal drawings for this application. Particularly, in the formal drawings reference numeral 44 appears twice. By amendment herein, one of these is corrected to -- 49 --, as appears on the informal drawings as originally filed with the application. No new matter is introduced by this amendment, and entry